

Power MOSFET, 180 A



SOT-227

PRODUCT SUMMARY				
V_{DSS}	100 V			
I _D DC	180 A			
R _{DS(on)}	$0.0065~\Omega$			
Туре	Modules - MOSFET			
Package	SOT-227			

FEATURES

- · Fully isolated package
- Easy to use and parallel
- Very low on-resistance
- Dynamic dV/dt rating
- Fully avalanche rated
- Simple drive requirements
- · Low drain to case capacitance
- Low internal inductance
- UL pending
- Compliant to RoHS directive 2002/95/EC

DESCRIPTION

5th Generation, high current density Power MOSFETs are paralled into a compact, high power module providing the best combination of switching, ruggedized design, very low on resistance and cost effectiveness.

The isolated SOT-227 package is preferred for all commercial-industrial applications at power dissipation levels to approximately 500 W. The low thermal resistance and easy connection to the SOT-227 package contribute to its universal acceptance throughout the industry.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Continuous drain current at V _{GS} 10 V		T _C = 25 °C	180		
	I _D	T _C = 100 °C	120	Α	
Pulsed drain current	I _{DM} ⁽¹⁾		720		
Power dissipation	P _D	T _C = 25 °C	480	W	
Linear derating factor			2.7	W/°C	
Gate to source voltage	V _{GS}		± 20	V	
Single pulse avalanche energy	E _{AS} (2)		700	mJ	
Avalanche current	I _{AR} ⁽¹⁾		180	Α	
Repetitive avalanche energy	E _{AR} (1)		48	mJ	
Peak diode recovery dV/dt	dV/dt (3)		5.7	V/ns	
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to + 150	°C	
Insulation withstand voltage (AC-RMS)	V _{ISO}		2.5	kV	
Mounting torque		M4 screw	1.3	Nm	

Notes

- (1) Repetitive rating; pulse width limited by maximum junction temperature (see fig. 8)
- $^{(2)}$ Starting T_J = 25 °C, L = 43 $\mu H,\ R_g$ = 25 $\Omega,\ I_{AS}$ = 180 A (see fig. 12)
- $^{(3)}~I_{SD} \leq 180~A,~dI/dt \leq 83~A/\mu s,~V_{DD} \stackrel{\circ}{\leq} V_{(BR)DSS},~T_{J} \leq 150~^{\circ}C$

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THERMAL RESISTANCE				
PARAMETER	SYMBOL	TYP.	MAX.	UNITS
Junction to case	R _{thJC}	-	0.26	°C/W
Case to sink, flat, greased surface	R _{thCS}	0.05	-	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain to source breakdown voltage	V(BR)DSS	V _{GS} = 0 V, I _D = 250 μA	100	-	-	V
Breakdown voltage temperature coefficient	$\Delta V_{(BR)DSS}/\Delta T_{J}$	Reference to 25 °C, I _D = 1 mA	-	0.093	-	V/°C
Static drain to source on-resistance	R _{DS(on)} (1)	V _{GS} = 10 V, I _D = 180 A	-	0.0065	-	Ω
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0	-	4.0	V
Forward transconductance	9 _{fs}	V _{DS} = 25 V, I _D = 180 A	93	-	-	S
Drain to source leakage current	,	V _{DS} = 100 V, V _{GS} = 0 V V _{DS} = 80 V, V _{GS} = 0 V, T _J = 125 °C	-	-	50	
	I _{DSS}		-	-	500	μA
Gate to source forward leakage		V _{GS} = 20 V	-	-	200	^
	I _{GSS}	V _{GS} = - 20 V	-	-	- 200	nA
Total gate charge	Q_g	I _D = 180 A	-	250	380	
Gate to source charge	Q _{gs}	V _{DS} = 80 V	-	40	60	nC
Gate to drain ("Miller") charge	Q_{gd}	V _{GS} = 10.0 V; see fig. 6 and 13 ⁽¹⁾	-	110	165	
Turn-on delay time	t _{d(on)}	V _{DD} = 50 V	-	45	-	
Rise time	t _r	I _D = 180 A	-	351	-	
Turn-off delay time	t _{d(off)}	$R_g = 2.0 \Omega$ (internal)	-	181	-	ns
Fall time	t _f	$R_D = 0.27 \Omega$, see fig. 10 ⁽¹⁾	-	335	-	
Internal source inductance	L _S	Between lead, and center of die contact	-	5.0	-	nH
Input capacitance	C _{iss}	V _{GS} = 0 V	-	10 700	-	
Output capacitance	C _{oss}	V _{DS} = 25 V	-	2800	-	pF
Reverse transfer capacitance	C_{rss}	f = 1.0 MHz, see fig. 5	-	1300	_	1

Note

 $^{^{(1)}~}$ Pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$

SOURCE-DRAIN RATINGS AND CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Continuous source current (body diode)	I _S	MOSFET symbol	=	-	180	^
Pulsed source current (body diode)	I _{SM} ⁽¹⁾	showing the integral reverse p-n junction diode.	-	-	720	A
Diode forward voltage	V _{SD} ⁽²⁾	T _J = 25 °C, I _S = 180 A, V _{GS} = 0 V	-	-	1.3	V
Reverse recovery time	t _{rr} (2)	T 05 °C 100 A; dl/dt 100 A/;;	-	300	450	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 180 \text{A}; \text{dI/dt} = 100 \text{A/}\mu\text{s}$	-	2.6	3.9	μC
Forward turn-on time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S + L _D)				

Notes

⁽¹⁾ Repetitive rating; pulse width limited by maximum junction temperature (see fig. 8)

⁽²⁾ Pulse width \leq 300 µs, duty cycle \leq 2 %

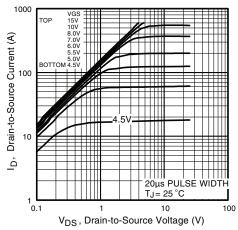


Fig. 1 - Typical Output Characteristics

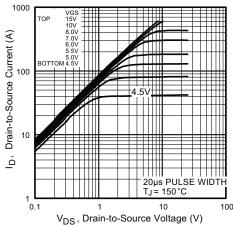


Fig. 2 - Typical Output Characteristics

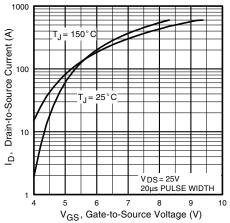


Fig. 3 - Typical Transfer Characteristics

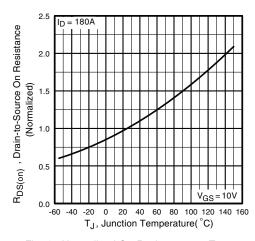


Fig. 4 - Normalized On-Resistance vs. Temperature

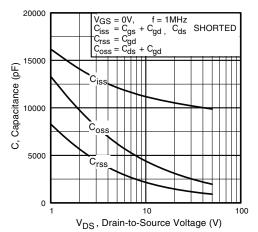


Fig. 5 - Typical Capacitance vs. Drain to Source Voltage

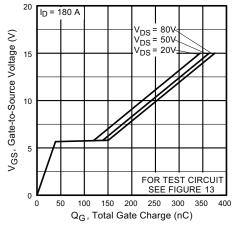


Fig. 6 - Typical Gate Charge vs. Gate to Source Voltage

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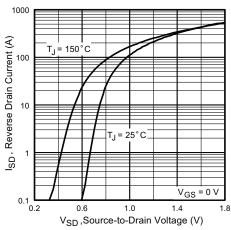


Fig. 7 - Typical Source Drain Diode Forward Voltage

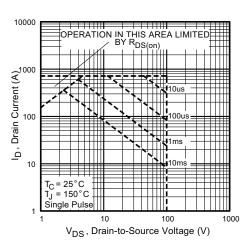


Fig. 8 - Maximum Safe Operating Area

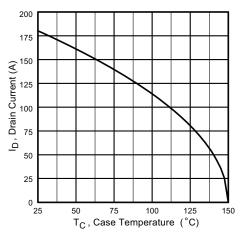


Fig. 9 - Maximum Drain Current vs. Case Temperature

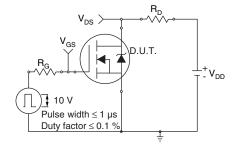


Fig. 10a - Switching Time Test Circuit

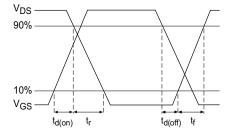


Fig. 10b - Switching Time Waveforms

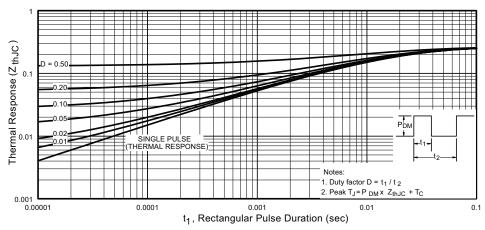


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction to Case

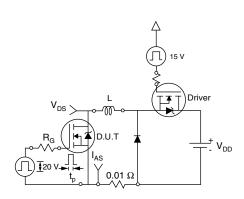


Fig. 12a - Unclamped Inductive Test Circuit

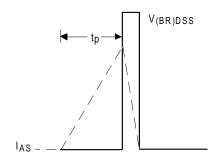


Fig. 12b - Unclamped Inductive Waveforms

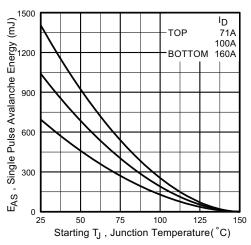


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

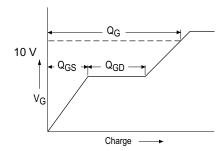


Fig. 13a - Basic Gate Charge Waveform

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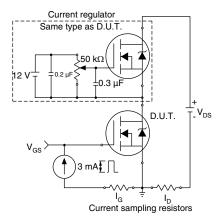


Fig. 13b - Gate Charge Test Circuit

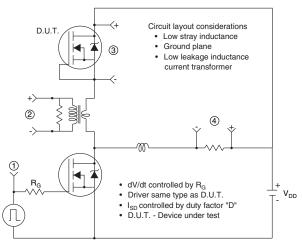
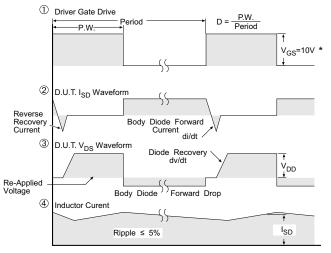


Fig. 13c - Peak Diode Recovery dV/dt Test Circuit



* V_{GS} = 5V for Logic Level Devices

Fig. 14 - For N-Channel Power MOSFETs

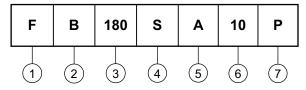


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Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code



- 1 Power MOSFET
- Generation 5 MOSFET silicon DBC construction
- 3 Current rating (180 = 180 A)
- 4 Single switch
- **5** SOT-227
- 6 Voltage rating (10 = 100 V)
- 7 P = Lead (Pb)-free

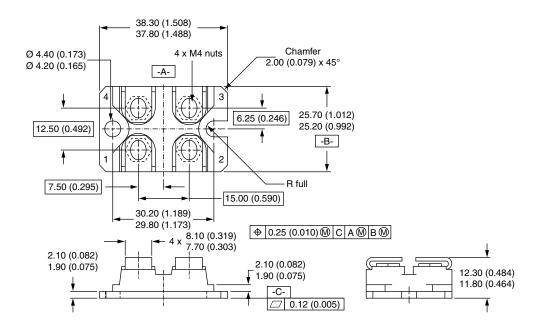
CIRCUIT CONFIGURATION					
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRA	AWING		
Single switch no diode	S	G (2) S (1-4)	Lead assignment S D 3 1 S G		

LINKS TO RELATED DOCUMENTS					
Dimensions www.vishay.com/doc?95036					
Packaging information	www.vishay.com/doc?95037				



SOT-227

DIMENSIONS in millimeters (inches)



Notes

- Dimensioning and tolerancing per ANSI Y14.5M-1982
- · Controlling dimension: millimeter

Document Number: 95036 Revision: 28-Aug-07



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Vishay

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